

**40W - 28V - 175MHz**  
**GOLD METALLISED MULTI-PURPOSE**  
**SILICON DMOS RF FET**

**FEATURES**

- METAL GATE
- EXTRA LOW  $C_{rss}$
- BROAD BAND
- SIMPLE BIAS CIRCUITS
- LOW NOISE
- HIGH GAIN

**APPLICATIONS**

- HF/VHF/UHF COMMUNICATIONS

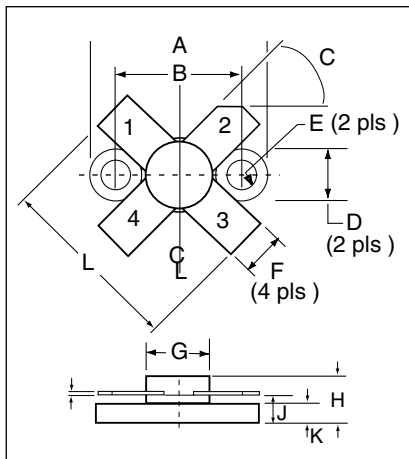
**ABSOLUTE MAXIMUM RATINGS**  
( $T_{CASE} = 25^{\circ}C$  unless otherwise stated)

$P_D$	Power Dissipation	87W
$BV_{DSS}$	Drain-source breakdown voltage	70V
$V_{GSS}$	Gate-source voltage	$\pm 20V$
$I_D$	Drain Current	10A
$T_{stg}$	Storage temperature	-65 to 150°C
$T_j$	Maximum operating junction temperature	200°C
$R_{THj-case}$	Thermal resistance junction-case	Max.2.0°C/W

**ELECTRICAL CHARACTERISTICS ( $T_{CASE} = 25^{\circ}C$  unless otherwise stated)**

Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Breakdown voltage, drain source $V_{GS}=0$ $I_D=100mA$	70			Vdc
$I_{DSS}$	Drain leakage current $V_{DS}=28V$ $V_{GS}=0$			2	mAdc
$I_{GSS}$	Gate leakage current $V_{GS}=20V$ $V_{DS}=0$			1	$\mu$ Adc
$V_{GS(th)}$	Gate threshold voltage $I_D=10mA$ $V_{DS}=V_{GS}$	1		7	Vdc
$g_{fs}$	Transconductance (300 $\mu$ s pulse) $V_{DS}=10V$ $I_D=2A$	1.6			mhos
$G_{PS}$	Common source power gain $P_O=40W$	16			dB
$\eta$	Drain efficiency $V_{DS}=28V$ $I_{DQ}=0.8A$	50			%
VSWR	Load mismatch tolerance $f=175MHz$	20:1			
$C_{iss}$	Input capacitance $V_{DS}=0V$ $V_{GS}=-5V$ $f=1MHz$			120	pF
$C_{oss}$	Output capacitance $V_{DS}=28V$ $V_{GS}=0$ $f=1MHz$			60	pF
$C_{rss}$	Reverse transfer capacitance $V_{DS}=28V$ $V_{GS}=0$ $f=1MHz$			5	pF

**DIMENSIONS**

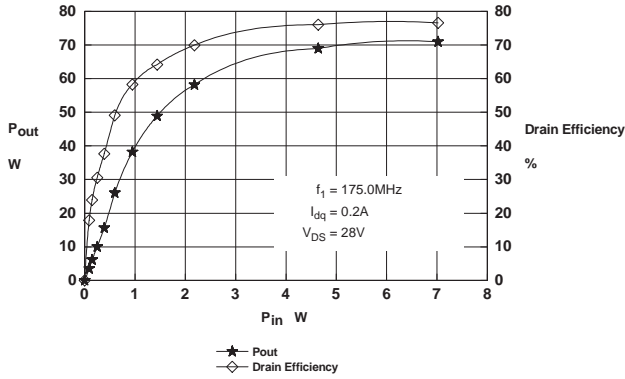


DM	Millimeter	TOL	Inches	TOL
A	24.76	.13	.975	.005
B	18.42	.13	.725	.005
C	45°	5°	45°	5°
D	6.35	.13	.250	.005
E	3.17 DIA	.13	.125 DIA	.005
F	5.71	.13	.225	.005
G	9.52 DIA	.13	.375 DIA	.005
H	6.60	REF	.260	REF
I	.13	.02	.005	.001
J	4.32	.13	.170	.005
K	2.54	.13	.100	.005
L	20.32	.25	.800	.010

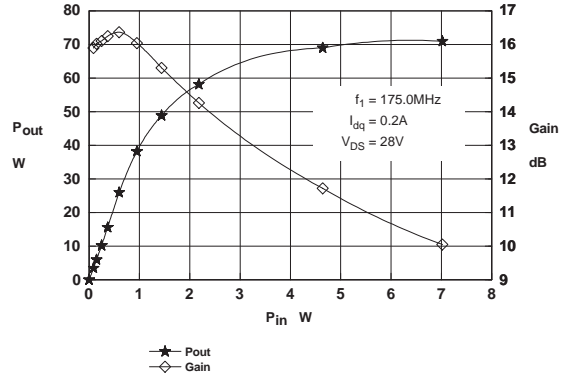
**HAZARDOUS MATERIAL WARNING**

The ceramic portion of the device between leads and metal flange is beryllium oxide. Beryllium oxide dust is highly toxic and care must be taken during handling and mounting to avoid damage to this area. THESE DEVICES MUST NEVER BE THROWN AWAY WITH GENERAL INDUSTRIAL OR DOMESTIC WASTE.

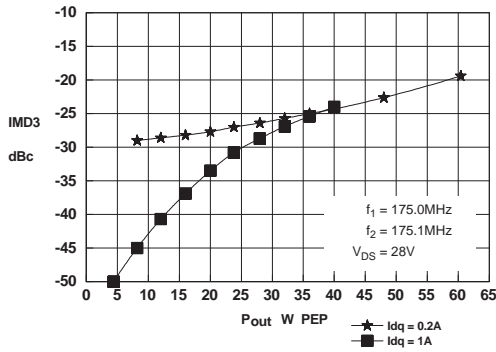
U.S. PATENTS 5,121,176 & 5,179,032  
GLOBAL PATENTS PENDING



**Figure 1 – Power Output and Efficiency vs. Power Input.**



**Figure 2 – Power Output & Gain vs. Power Input.**



**Figure 3 – IMD vs. Output Power.**

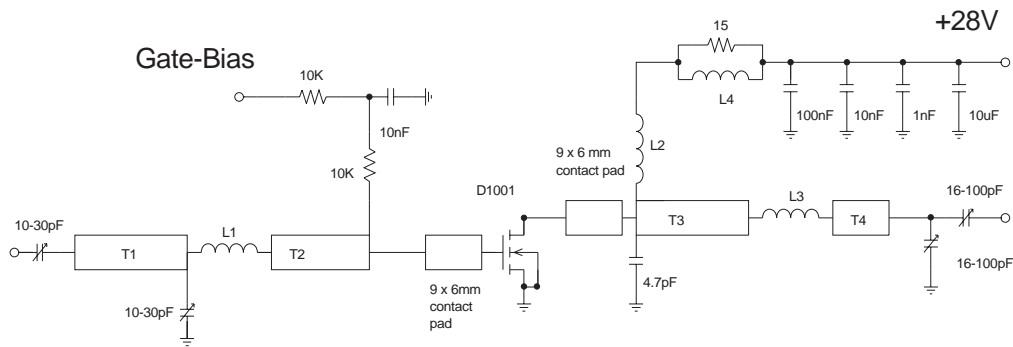
**D1002**  
**OPTIMUM SOURCE AND LOAD IMPEDANCE**

Frequency MHz	$Z_S$ $\Omega$	$Z_L$ $\Omega$
175MHz	$3.8 + j6.5$	$4.6 + j0.4$

**Typical S Parameters**

! Vds=28V Idq=0.2A  
# MHz S MA R 50

!Freq MHz	S11		S21		S12		S22	
	mag	ang	mag	ang	mag	ang	mag	ang
50	0.76	-144	15.6	86	0.026	1	0.58	-119
100	0.79	-155	7.1	61	0.021	-9	0.66	-132
150	0.84	-163	4.2	43	0.012	-3	0.74	-144
200	0.87	-169	2.7	33	0.009	47	0.81	-154
250	0.90	-176	1.9	23	0.016	76	0.85	-163
300	0.92	177	1.5	20	0.025	87	0.88	-172
350	0.94	170	1.1	11	0.033	85	0.91	-180
400	0.96	163	0.9	6	0.046	82	0.94	172
450	0.97	156	0.7	-2	0.051	78	0.96	165
500	0.98	150	0.6	-8	0.062	76	0.98	157
550	0.98	144	0.4	-12	0.068	74	0.98	152
600	0.98	141	0.4	-14	0.078	67	0.98	148



## D1002 175MHz TEST FIXTURE

Substrate 1.6mm PTFE/glass, Er=2.5  
All microstrip lines W=4.4mm

T1 10mm  
T2 13mm  
T3 12mm  
T4 4mm

L1 1.5 turns 22swg enamelled copper wire, 6mm i.d.  
L2 10 turns 19swg enamelled copper wire, 6mm i.d.  
L3 1.5 turns 22swg enamelled copper wire, 6mm i.d.  
L4 13.5 turns 19swg enamelled copper wire on  
Siemens B64920A618X830 ferrite core

\*D1002

\*PSPICE MODEL FOR POINT NINE RF N-CHANNEL VERTICAL DMOS POWER FET

\*May 2004

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*          _____GATE
*          I   _____DRAIN
*          I   I   _____SOURCE
*          I   I   I
.SUBCKT D1002  10  20  30
*Cin1,Cin2 & Lin model the input side of the package
Cin1  10   30   0.31p
Lin   10   11   0.64n
Cin2  11   30   0.24p
LG    11   12   1n    ;Gate bond wire inductance
CGS   12   13   92p   ;Gate-source capacitance
MOS   14   12   13    13  D1002 L=0.9U W=0.112    ;D G S B LEVEL1
JFET  16   13   14    D1002                      ;D G S
DBODY 13   16   D1002                              ;P N
LS    13   30   0.7n  ;Source bond wire inductance
CGD   12   16   2p    ;Gate-drain feedback capacitance

*Cout1,Cout2 & Lout model the output side of the package
Cout1 16   30   0.65p
Lout   16   20   1.5n
Cout2 20   30   0.6p

.MODEL D1002 NMOS (VTO=4.76 KP=2.811E-5 LAMBDA=0.032 RD=0.038 RS=0.153)
.MODEL D1002 NJF (VTO=-4.3 BETA=0.5 LAMBDA=0.54)
.MODEL D1002 D (CJO=164.4P RS=0.25 VJ=0.7 M=0.35 BV=75)

.ENDS
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